

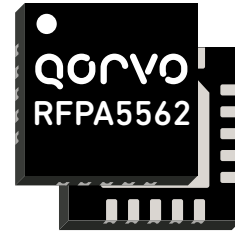
Product Overview

The Qorvo® RFPA5562 is a three-stage power amplifier (PA) designed for Wi-Fi 802.11a/n/ac/ax systems. The compact form factor and integrated matching minimizes layout area in the application and greatly reduces the number of external components.

Performance is focused on optimizing the PA for a 5V supply voltage that conserves power consumption while maintaining the highest linear output power and leading edge throughput.

A key feature is the integration of a DC power detector with logarithmic feedback across power which enables power control to lower powers and enables the possibility to calibrate against a constant slope for applications which use higher gain antennas or end users wanting to reduce device calibration time in production.

The RFPA5562 integrates a 5GHz power amplifier (PA), regulator and power detector into a single device.

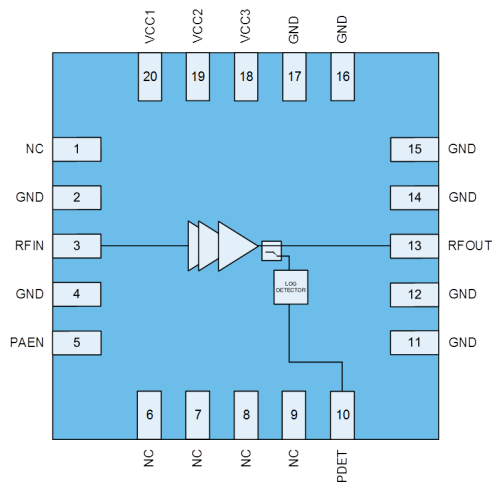


20 Pin 4x4 mm QFN Package

Key Features

- 4900 – 5925 MHz
- $P_{OUT} = +18\text{dBm}$ MCS11 HE80 -43dB Dynamic EVM
- $P_{OUT} = +23\text{dBm}$ MCS9 VHT80 -35dB Dynamic EVM
- $P_{OUT} = +25\text{dBm}$ MCS7 HT20/40 -30dB Dynamic EVM
- $P_{OUT} = +27\text{dBm}$ MCS0 HT20 Spectral Mask Compliance
- Optimized for +5 V Operation
- 33 dB Tx Gain
- Integrated DC Power Detector
- Input and Output Matched to 50Ω

Functional Block Diagram



Top View

Applications

- Access Points
- Wireless Routers
- Residential Gateways
- Customer Premise Equipment
- Internet of Things

Ordering Information

Part Number	Description
RFPA5562SB	Sample bag with 5 pieces
RFPA5562SQ	Sample bag with 25 pieces
RFPA5562SR	7" reel with 100 pieces
RFPA5562TR13	13" reel with 2,500 pieces
RFPA5562PCK-410	Assembled Evaluation Board

Absolute Maximum Ratings

Parameter	Conditions	Rating
DC Supply Voltage		-0.5 to +6 V
Control Voltage	PAEN	-0.5 to +6 V
Storage Temperature		-40 to 150 °C
Junction Temperature	MTTF > 1.5x10 ⁶ hours	160 °C
	MTTF > 1.0x10 ⁶ hours	170 °C
RF Input Power at RFIN	Into 50 Ω Load for 802.11a/n/ac/ax (No Damage) *R1=0Ω	+10 dBm
	Into 10:1 VSWR Load for 802.11a/n/ac/ax (No Damage) *R1=15Ω	+15 dBm

Exceeding any one or a combination of the Absolute Maximum Rating conditions may cause permanent damage to the device. Extended application of Absolute Maximum Rating conditions to the device may reduce device reliability. This is an InGaP device designed for high duty cycle applications with T_J>30 °C over ambient.

For R1 placement, refer to Evaluation Board Schematic

Recommended Operating Conditions

Parameter	Min.	Typ.	Max.	Units
Operating Frequency	5180		5925	MHz
Extended Operating Frequency	4900		5925	MHz
Device Voltage (V _{CC})	+4.75	+5	+5.25	V
Control Voltage – High	+1.7	+3	+3.3	V
Control Voltage – Low	0		+0.5	V
T _{OPERATING} *	-40		+85	°C

Electrical specifications are measured at specified test conditions. Specifications are not guaranteed over all recommended operating conditions. * T_{OPERATING} is temperature at package ground.

Electrical Specifications

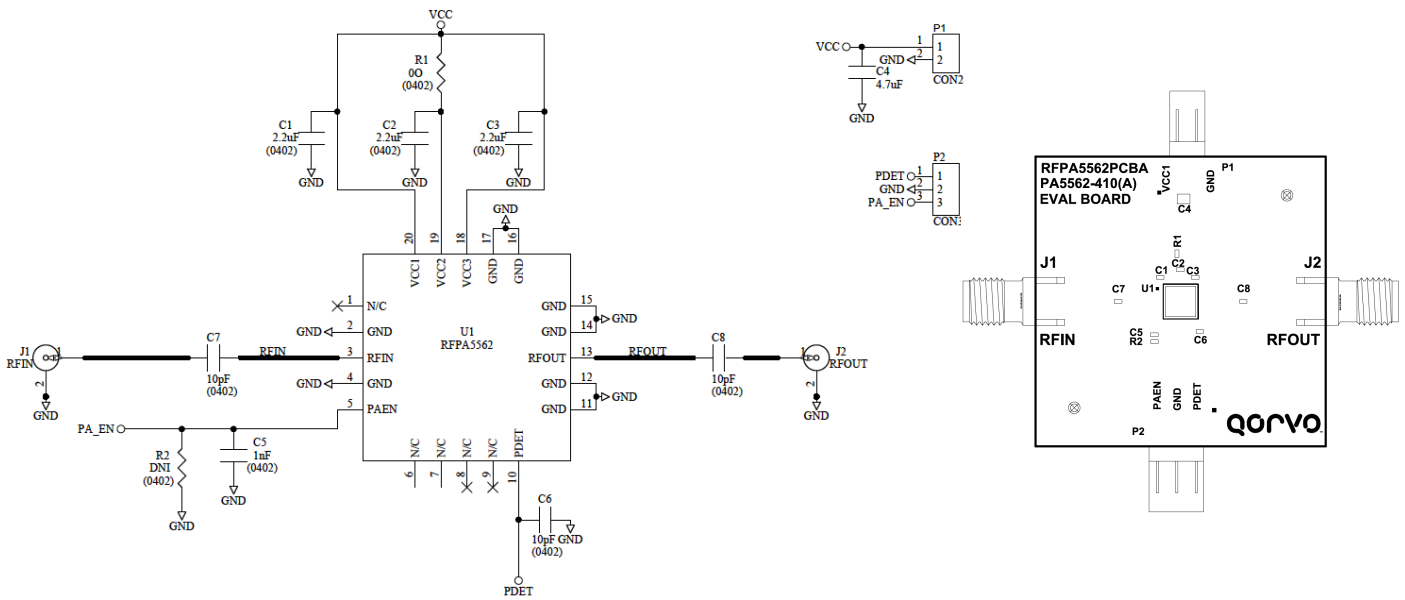
Parameter	Conditions	Min.	Typ.	Max.	Units
Transmit (RFIN-RFOUT) Mode	Unless otherwise noted: V_{CC}=5V, T=+25°C, PA_EN=High				
11ax HE80 Output Power Dynamic EVM	MCS11 1024QAM		17		dBm
				-43	dB
11ac VHT80 Output Power	MCS9 1024QAM		21		dBm
				-40	dB
11ac VHT160 Output Power	MCS9 256QAM		22		dBm
				-35	dB
11ac VHT80 Output Power Dynamic EVM	MCS9 256QAM	22	23		dBm
				-35	dB
11n HT20/40 Output Power Dynamic EVM	MCS7 64QAM	23.5	25		dBm
				-30	dB
Margin to VHT160 Spectral Mask	P _{OUT} = +23 dBm, 11n MCS0		5	0	dBc
Margin to VHT80 Spectral Mask	P _{OUT} = +25 dBm, 11n MCS0		5	0	dBc
Margin to HT20 Spectral Mask	P _{OUT} = +27 dBm, 11n MCS0		5	0	dBc
Gain		31	33		dB

Parameter	Conditions	Min.	Typ.	Max.	Units
Gain Variation	T= -40 to +85 °C	-2.5		+2.5	dB
Out of Band Gain	f = 3300-3800MHz		-15	-5	dB
	f > 7000MHz			12	dB
RFIN Port Return Loss			12		dB
RFOUT Port Return Loss			9		dB
Quiescent Current	RF Off		150	165	mA
Operating Current	P _{OUT} = +17 dBm		200	225	mA
	P _{OUT} = +23 dBm		295	320	mA
	P _{OUT} = +27 dBm		415	450	mA
2 nd Harmonics	P _{OUT} = +27 dBm 802.11a 6 MBps		-40	-35	dBm/MHz
3 rd Harmonics	P _{OUT} = +27 dBm 802.11a 6 MBps		-40	-35	dBm/MHz
DC Power Detect Voltage	RF Off		0.25		V
	P _{OUT} = 0 dBm		0.28		V
	P _{OUT} = +27 dBm		0.81		V
DC Power Detector Slope	P _{OUT} = 0 to +27 dBm		22		mV/dB
GENERAL SPECIFICATIONS	Unless otherwise noted: V_{CC}=5V, T=+25°C,				
Control Current - High			1	5	μA
Leakage Current	RF Off. V _{PAEN} = 0V		0.2	10	μA
TX Output P _{1dB}	CW		+32		dBm
Ramp ON/OFF Time	10<->90% Ref from Control Voltage to RF Power		200		nS
PA Stability - Output VSWR	CW No Spurious above -41.25 dBm/MHz		6:1		
Output Power Range		0		27	dBm
Thermal Resistance, θ _{jc}	Junction to Case		25		°C/W

Logic Truth Table

Mode	PA_EN
Transmit	High
Idle	Low

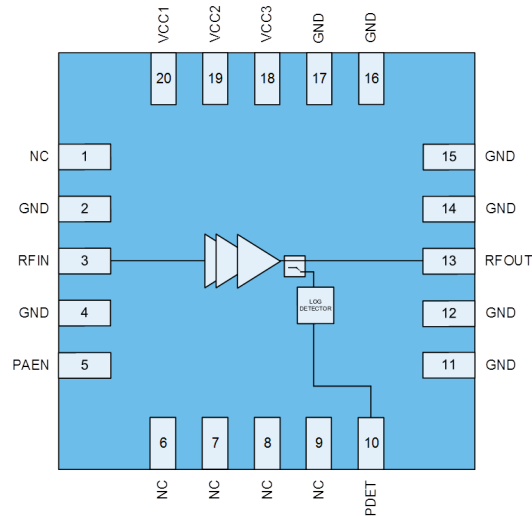
Evaluation Board Schematic and Layout



Bill of Material

Ref. Des.	Value	Description	Manuf.	Part number
-	-	Printed Circuit Board		
U1	-	5GHz Wi-Fi Power Amplifier	Qorvo	RFPA5562
C6, C7, C8	10 pF	Capacitor, Chip, 5%, 50V, C0G, 0402	Murata	GRM1555C1H100JA01D
C5	1000 pF	Capacitor, Chip, 10%, 50V, X7R, 0402	Murata	GRM155R71H102KA01D
C1, C2, C3	2.2 μ F	Capacitor, Chip, 10%, 6.3V, X5R, 0402	Taiyo Yuden	RM JMK105BJ225KV-F
R1	0 Ω	Resistor, Chip, 5%, 1/10W, 0402	Kamaya	RMC1/16SJPTH
R2	-	Do Not Install		

Pin Configuration and Description

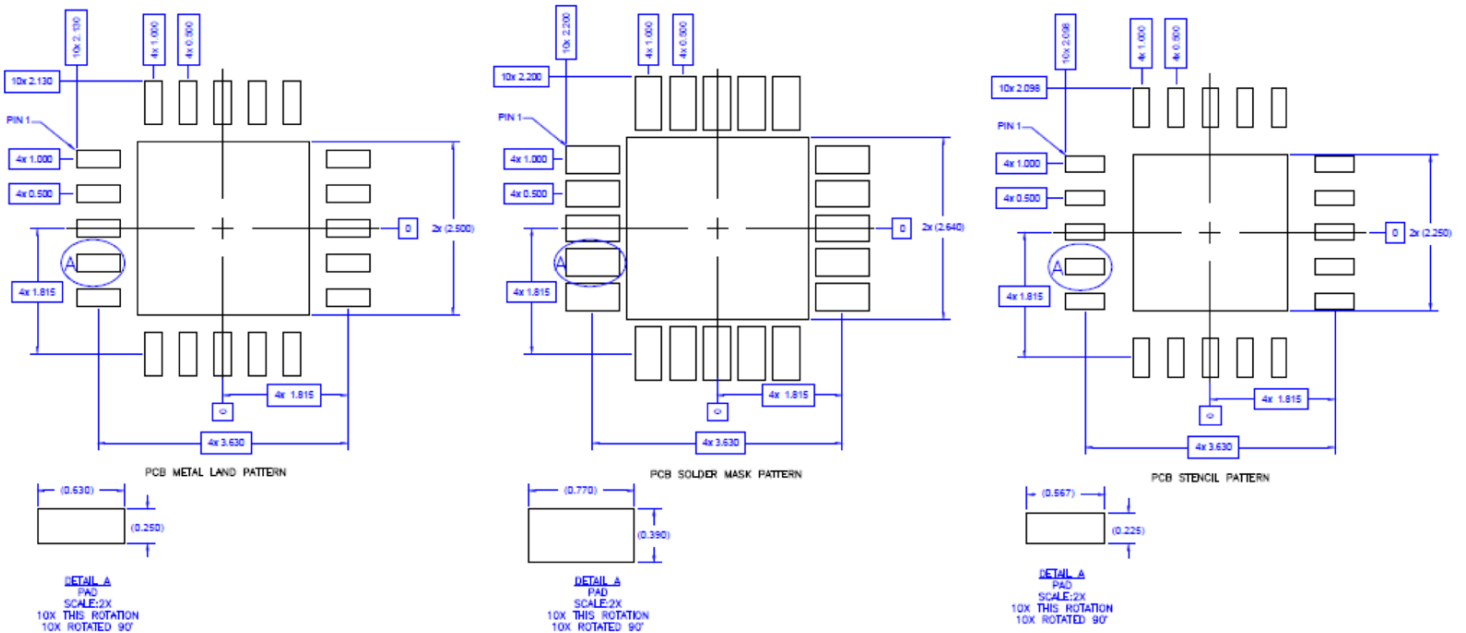
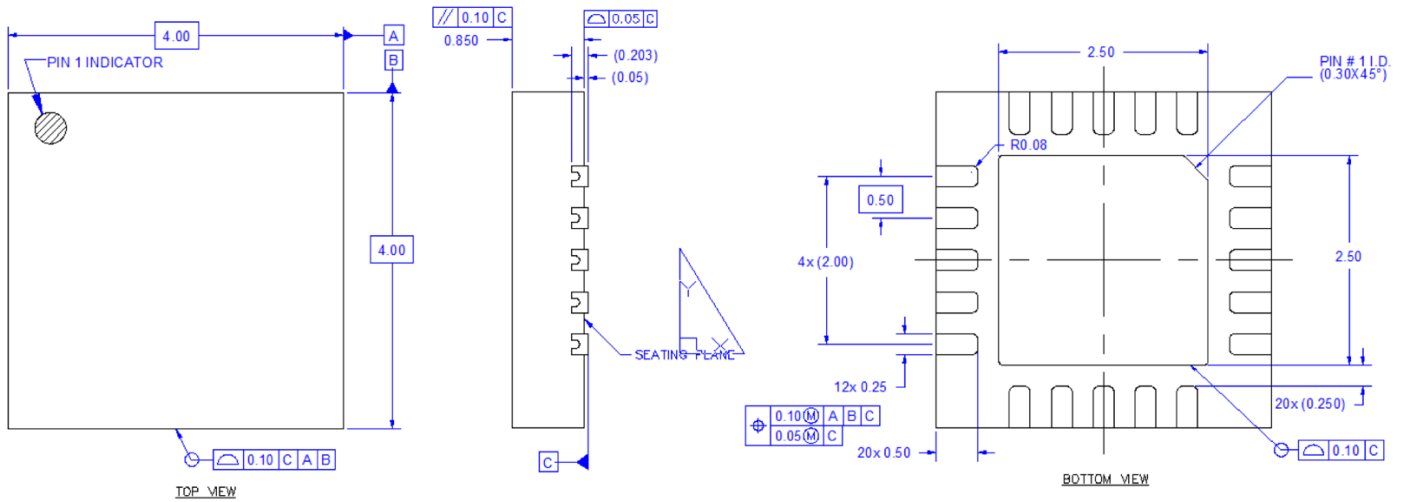


Top View

Pin Number	Label	Description
1	NC	No electrical connection.
2	GND	Ground connection.
3	RFIN	RF input. Internally matched to 50 Ω and DC Shorted. External DC blocking capacitor required.
4	GND	Ground connection.
5	PA_EN	Input enable bias voltage (regulated internally.)
6	NC	No electrical connection.
7	NC	No electrical connection.
8	NC	No electrical connection.
9	NC	No electrical connection.
10	PDET	DC power detector. Provides an output voltage proportional to the RF output power level
11	GND	Ground connection.
12	GND	Ground connection.
13	RFOUT	RF output. Internally matched to 50 Ω and DC shorted. External DC blocking capacitor required.
14	GND	Ground connection.
15	GND	Ground connection.
16	GND	Ground connection.
17	GND	Ground connection.
18	VCC3	3 rd stage supply voltage
19	VCC2	2 nd stage supply voltage
20	VCC1	1 st stage supply voltage
Backside Paddle	GND	RF/DC ground. Use recommended via pattern to minimize inductance and thermal resistance. See PCB Mounting Pattern for suggested footprint.

Mechanical Information

Dimensions and PCB Mounting Pattern



Notes:

1. All dimensions are in millimeters. Angles are in degrees.
2. Dimension and tolerance formats conform to ASME Y14.4M-1994.
3. The terminal #1 identifier and terminal numbering conform to JESD 95-1 SPP-012.